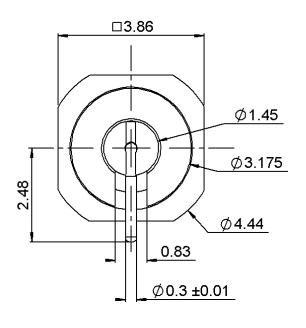
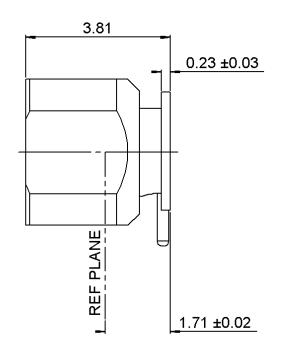


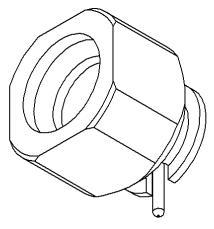


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All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER	GOLD OVER NICKEL
Center contact	BERYLLIUM COPPER	GOLD OVER NICKEL
Outer contact		-
Insulator	PEEK	
Gasket	-	
Others parts	-	-
-	-	-
-	-	-



Technical Data Sheet

SMT PLUG RECEPTACLE SMOOTH BORE - REEL OF 500

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			TART NOMBER NEOTOG

PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance Ω Frequency GHz 0-65* VSWR 0,0000 x F(GHz) Maxi

√F(GHz) dB Maxi Insertion loss 0.12* RF leakage - F(GHz)) dB Maxi NA Voltage rating 335 Veff Maxi Dielectric withstanding voltage 500 Veff mini Insulation resistance 5000 $M\Omega$ mini

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating End N mini Axial force – Opposite end 6.7*** N mini NA Torque N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini Nominal Weight (Add +15% for max 0,2740

weight)

ENVIRONMENTAL

Operating temperature -65/+165 °C Hermetic seal NA Atm.cm3/s Panel leakage NA

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

- *Coaxial transmission line only
- ** 1.15 to 12GHz
- ** 1.35 to 20GHz
- **Performance strongly depends on layout and PCB material
- ***after soldering on PCB



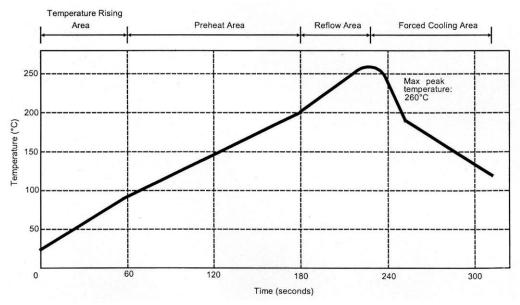


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SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 - Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow.

 Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

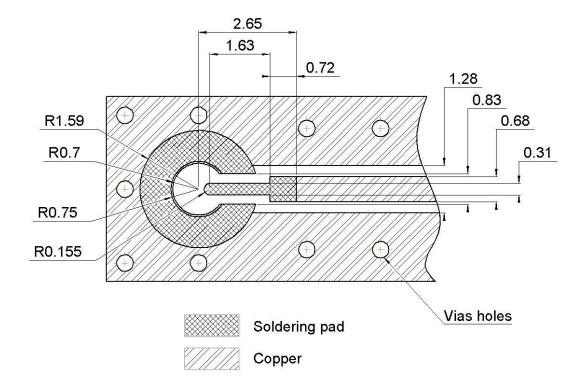




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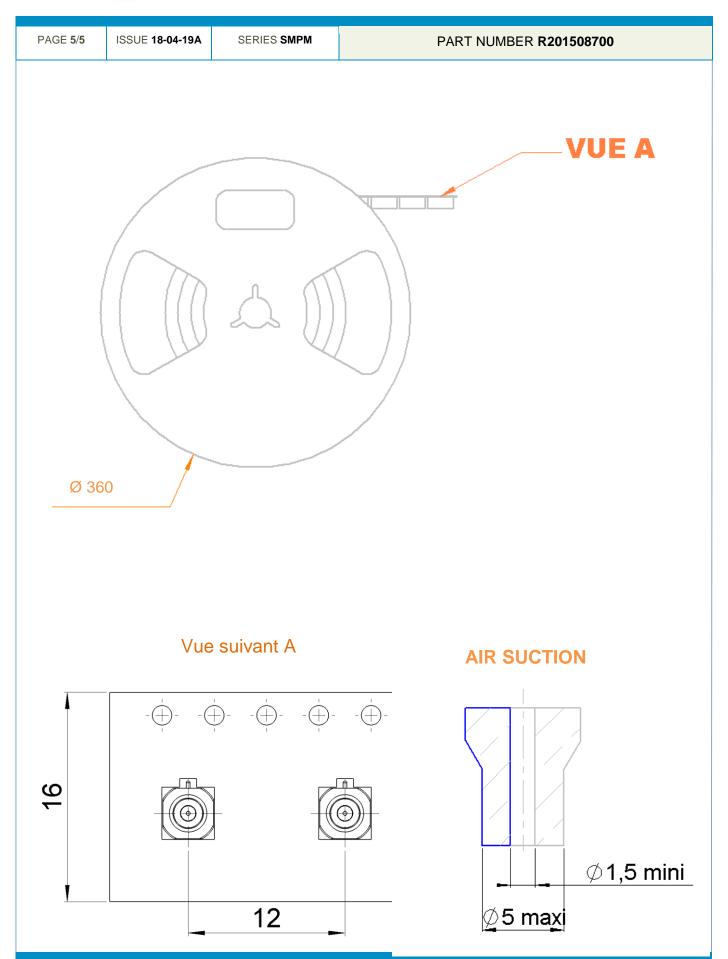
RECOMMENDED PAD DIMENSIONS

Substrat: RT5880 thickness 0.254 mm, with copper layer 35µm on both sides. Add vias between both sides along upper ground plane according to engineering practise.









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